



2812 07  
524.2

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

re patent application of: ) Before the Examiner  
)  
Harry Hedler et al. )  
)  
Serial No: 09/806,401 ) Group Art Unit:  
)  
Filed: October 22, 2001 )  
)  
Electronic Module, Especially a Multichip )  
Module, with Multi-Layer Metallization and )  
Corresponding Production Method )

**INFORMATION DISCLOSURE STATEMENT**

Applicants hereby submit the attached documents listed on the attached PTO Form 1449 in accordance with 37 CFR §1.97(b)(3), as these documents are being submitted before the first Office Action. Copies of the cited items are enclosed in accordance with 37 C.F.R. § 1.98.

The filing of this Information Disclosure Statement shall not be construed as an admission that the information cited is, or is considered to be, material to patentability as defined in § 1.56(b), or that these documents are prior art.

It is believed that no fee is required for consideration of the submitted items. Should any fee be required, however, please charge such fee to Deposit Account No. 02-0387, but not to include any payment of issue fees.

Respectfully submitted,

Eric J. Groen, Reg. No. 32,230  
BAKER & DANIELS  
205 West Jefferson Blvd., Suite 250  
South Bend, IN 46601  
(219) 234-4149

I hereby certify that this correspondence is being deposited with the U.S. Postal Service as First Class Mail in an envelope addressed to: Commissioner of Patents and Trademarks, Washington, D.C. 20231 on: May 3, 2002.

Michelle L. Watson

Dated: May 3, 2002

RECEIVED  
MAY -9 2002  
TECHNOLOGY CENTER 2800

